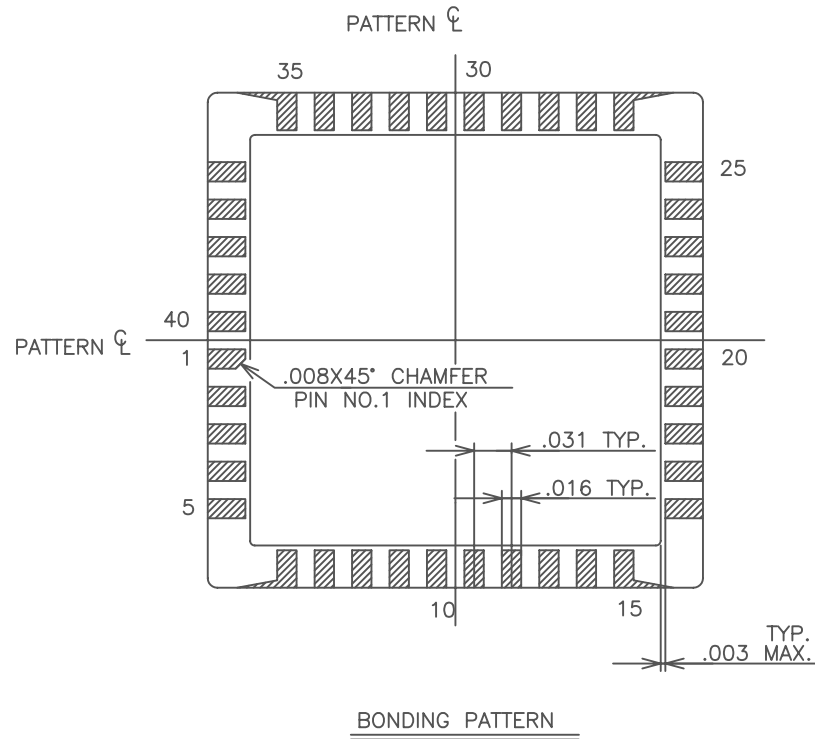


SSM P/N CSB04057



NOTES.

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.50 OHMS MAX.

CONTROLLED 8-18-03

MODIFICATION						NAME 40 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.F.	CHECKED A.F. K.K.	APPROVED T.A.	DATE JUN.23.'87
						SCALE 10 / 1	MATERIAL				
	△ REDRAWN	DEC.1.'95	K.I	H.S/S.F	T.A						
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S88423-B		SHEET 2/2	

